Product Bulletin

Document #:PB25149Z
Issue Date:20 Dec 2022

Title of Change:	NCV68061 - Product robustification
Effective date:	01 Jan 2023
Contact information:	Contact your local onsemi Sales Office or Juraj.Kremmer@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	New masks to increase passivation to pad metal overlap

Sites Affected:

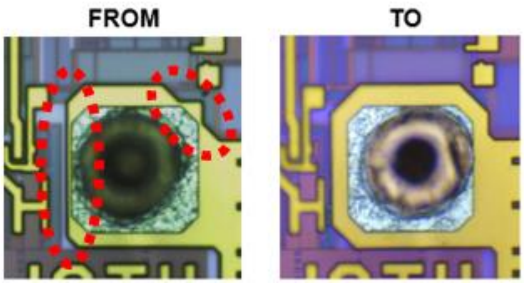
onsemi Sites	**External Foundry/Subcon Sites**
onsemi, Gresham United States	None

Description and Purpose:

This is a product robustness improvement. In order to make the product more robust against potential issues, the passivation to pad metal overlap has been increased from minimum 2.12 um to minimum 6 um. The change is in the passivation to pad metal overlap only, done by increasing the pad metal dimensions.
No change to the bond pad opening dimensions.
No change in the pad composition and pad metal thickness.

	From	To
Minimum passivation to pad metal overlap	2.12 um	6 um

Representative picture of the passivation to pad metal overlap increase:



There are no product material changes as a result of this change.
There is no product marking change as a result of this change.

As circumspection, reliability evaluation was performed relative to the new masks.

Reliability Data Summary:

QV DEVICE NAME: NCV68061SNAIT1G
RMS: S85275
PACKAGE: TSOP-6

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	2016 hrs	0/160
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/247
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/167

List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

NCV68061SNAIT1G		